November 21, 2025

To whom it may concern

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Joint Technical Presentation with Japan Electronic Material Corp at "SWTest Asia 2025"

We are pleased to announce that today, at the international conference "SWTest (Semiconductor Wafer Test) Asia 2025"-specializing in semiconductor wafer and die-level testing technologies in the Asia region-we made a joint technical presentation with Japan Electronic Material Corp.

Our company has set "Building Strategic Partnerships" as a key objective in our mid-term management plan, aiming to develop new products efficiently through alliances with other companies. We will continue to strive to enhance corporate value by actively building partnerships.

■Presentation Content

- **Title**

  「New Method for Mounting Lens Module on Probe Card for CMOS Image Sensors testing」

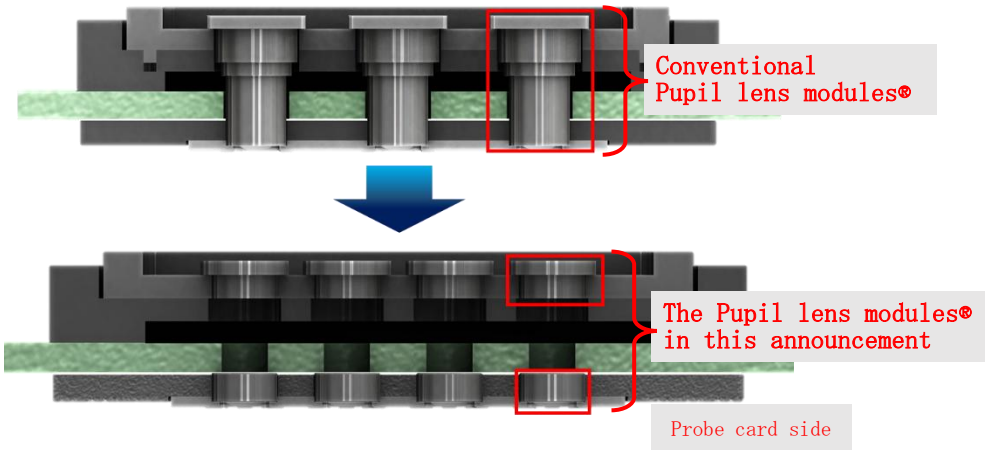
- **Presenter**

  Tomonao NAKASHIMA (Japan Electronic Material Corp - Japan)
  Hiroki TSUTSUMI (INTER ACTION Corporation - Japan)

- **Content**

  The conventional Pupil lens modules® were connected to the probe card using a dedicated fixture composed of multiple parts. Consequently, mechanical variations in the fixture caused misalignment between the Pupil lens modules® and the sensor. This time, we successfully reduced misalignment by developing a technology that splits the Pupil lens modules® into two parts and connects some lenses directly to the probe card. This new structure also contributes to miniaturizing both the lenses and the probe card aperture.

＜Conventional Pupil lens modules® and the Pupil lens modules® of this announcement＞



・Technical value

By utilizing this technology, it is possible to enhance the optical performance of the Pupil lens modules®, increase the number of simultaneous measurements, and further improve the electrical characteristics of probe cards. This is expected to enable the realization of a higher-quality and more efficient image sensor testing environment.

＜Supplement＞

■ About "SWTest Asia 2025"

Overview	SWTest is an international conference on semiconductor wafer and die-level test technology with over 30 years of history in the United States. SWTest Asia is a related event targeting the Asian region, attracting approximately 700 participants from over 15 countries at its 2024 event.
Event Dates	Thursday, November 20, 2025 - Saturday, November 22, 2025
Venue	Hilton Fukuoka Sea Hawk, Japan
Presentation Date and Time	Friday, November 21, 2025, 2:00 PM to 2:30 PM
Program Details	https://www.swtestasia.org/program/

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